

05-27-1999

FORM PTO-1595

(Rev. 6-93)
OMB No. 0651-0011 (exp. 4/94)



101048658

V COVER SHEET U.S. DEPARTMENT OF COMMERCE

Patent and Trademark Office
Atty Dkt No. 99 P 7594 US

To the Honorable Court, please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Sumit PANDEY

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)

Name: Infineon Technologies Corporation

Internal Address: _____

Street Address: 10950 North Tantau Avenue

City: Cupertino State: CA ZIP: 95014

Additional name(s) & address(es) attached? Yes No

jc525 U.S. PTO
09/315090
05/19/99

3. Nature of conveyance:

Assignment Merger
 Security Agreement Change of Name
 Other _____

Execution Date: May 6, 1999

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Elsa Keller

Internal Address: _____

Siemens Corporation

Intellectual Property Department

Street Address: 186 Wood Avenue South

City: Iselin State: NJ ZIP: 08830

6. Total number of applications and patents involved: 1

7. Total Fee (37 CFR 3.41) \$ 40.00

Enclosed

Authorized to be charged to deposit account

8. Deposit Account No.

19-2179

DO NOT USE THIS SPACE

9. Statement and signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Stanton C. Braden
Name of Person Signing
Reg. No. 32,556

[Signature]
Signature

May 19, 1999
Date

Total number of pages including cover sheet, attachments, and document: 3

09315090
00000010 192179
40.00 CH
05/27/1999 DNGUYEN
01 FC:561

ASSIGNMENT

For good and valuable consideration, I, **Sumit PANDEY**, residing at 17A Surrey Lane, Wappingers Falls, NY 12533, a citizen of India,

Hereby sell, assign, and transfer to Infineon Technologies Corporation, a corporation organized and existing under the laws of the state of Delaware, having its principal place of business at 10950 North Tantau Ave., Cupertino, CA 95014,

hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewithin, and is entitled:

SYSTEM FOR DISPENSING POLISHING LIQUID DURING CHEMICAL MECHANICAL POLISHING OF A SEMICONDUCTOR WAFER

and in and to said application and all divisional, continuing substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

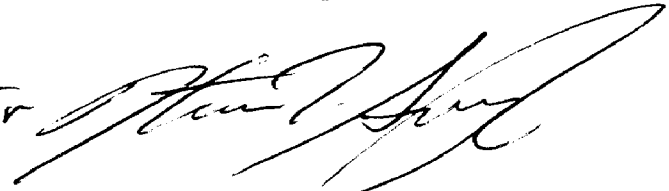
Agree that Assignee may apply for and receive Letters Patent for said improvements in its own name, and that, when requested, without charge to but at the expense of said Assignee, their successors, assigns, and legal representatives to carry out in good faith the intent and purpose of this agreement, the undersigned will execute all divisional, continuing substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date: 05/06/99


Sumit PANDEY

Witness: Kenneth T. Settlemyer, Jr
(type name)



Witness: THOMAS W. DYER
(type name)

